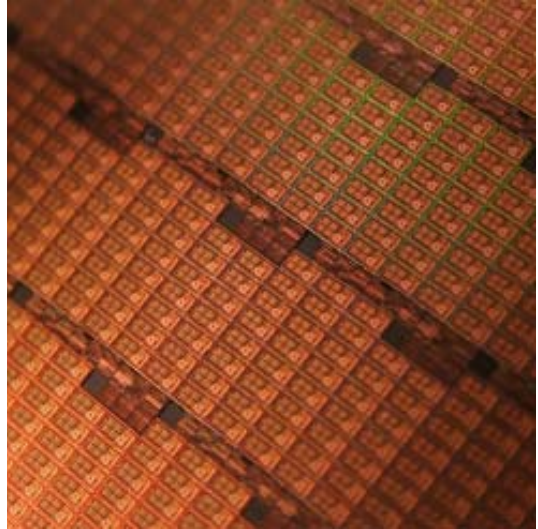


PRESS RELEASE

For immediate release

New High Speed Copper Eliminates Wafer Bowing

Cranston, Rhode Island – Technic Inc., an international leader in advanced electroplating process technology, has announced the release of Technic’s Semiplate Cu. Designed for Semiconductor plating applications where single sided copper electroplating of large areas is required, Semiplate Cu is a high speed copper plating process capable of depositing copper at 40 – 60 ASF with virtually no internal stress in the deposit. The deposit characteristics allow for coverage to a single side of the wafer without any undesirable bowing of the substrate. Technic Semiplate Cu removes the former limitations for large area copper plating on single sided wafers.



Steve Schaefer, Vice President of Global Business Operations, stated “In this challenging global environment, Technic continues to invest in R&D and bring innovative solutions to market for our customers. Technic Semiplate Cu is an enabling technology that offers our customers a level of design flexibility not currently available in today’s market.”

Technic is a US based, private, financially strong corporation. For over 60 years, Technic has been a global supplier of proprietary chemistries, specialized custom finishing equipment, engineered powders, and analytical control systems to the electronic component, printed circuit board, semiconductor, photovoltaic, and industrial finishing industries.

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For information on Technic and Technic products go to: www.technic.com or contact Technic at (401) 781-6100.